Q7800 Automatic Wedge Bonder

Designed for Complex Hybrid, Opto-Electronic and I.C. Assembly Requirements

Specifications*

**Standard Features – Hardware**

- Rotary Bond Head
- On-Axis Linear Theta Encoder
- 4" X 3.65" table travel
- Programmable U/S Generator
- Matrox Pattern Recognition System
- Flat Panel Monitor
- Stereo Zoom 4 Microscope
- Wireless Mouse
- Galil Motion Control System
- Windows™ XP OS
- Fiber Optic Light Source

**Specifications**

Wire - Aluminum or Gold

- Size Range
  - 0.0007" – 0.003" (17.8 – 76.2 microns)
- Maximum Wires Per Device
  - Unlimited

Spool Diameter

- 2.0" (50.8)

Wire Feed Angle

- 30°, 38°, 45°, 60°

Bonding Speed per Wire

- 600 ms pending application

**XY Table**

- Resolution
  - ± 0.0000625" (1.6 microns)
- Bonding Pitch
  - ± 0.00275" (69.9 microns)

**Standard Features – Software**

- Point and Click Bond Targeting
- Simple, Intuitive Programming
- Easy Bond Process Editing
- Extensive Program Storage
- Bond Parameter Library
- Unlimited Wire Program Storage
- Table Tear Capability
- Multiple Stitch Bonding
- Program Wire Groups for Multi-device, High Wire Count Hybrids

**Options**

- Custom Software
- Programmable Temperature Controller
- Universal Workholder – Heated or Ambient
- Additional Fiber Optic Light Source

**Accessories**

- Ethernet Adapter for Networking Bonders

**Miscellaneous**

- Remote Diagnostics Capability
- CE Mark

**Facilities**

- Electric - 120 VAC, 50/60 Hz, 15A
- N2 or clean, dry air for gold wire
- Vacuum / Air as required for workholder

**Dimension/Weight**

- Height: 72" (183 cm)
- Width: 39" (99 cm)
- Depth: 34.5" (88 cm)
- Table Height: 40" (102 cm)
- Weight: 600 pounds (273 Kg)
- Crated Weight: 750 pounds (341 Kg)

* Subject to Change

12/01/14